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## ABSTRACT OF THE DISCLOSURE

Within a method for fabricating a semiconductor integrated circuit microelectronic fabrication there is first provided a first There is then formed over the first semiconductor substrate. semiconductor substrate at least one microelectronic device to form from the first semiconductor substrate a partially fabricated semiconductor integrated circuit microelectronic fabrication. Within the method there is also provided a second substrate. There is also formed over the second substrate, in inverted order, a dielectric isolated metallization pattern intended to mate with the semiconductor integrated circuit partially fabricated microelectronic fabrication. Finally, there is then laminated the integrated circuit fabricated semiconductor partially microelectronic fabrication with the second substrate to mate the circuit integrated semiconductor fabricated partially dielectric isolated microelectronic fabrication with the metallization pattern to thus form a laminated completely integrated circuit microelectronic fabricated semiconductor The method provides for enhanced efficiency when fabrication. fabricating semiconductor integrated circuit microelectronic fabrications.